

This listing of claims will replace all prior versions of claims in the application.

Claims 1-28. (cancelled).

Claim 29. (currently amended) A positive-acting photoresist composition comprising a photoacid generator and a polymer,
the polymer 1) being substantially free of aromatic groups; and 2) comprising polymerized acrylate groups and pendant acid-labile groups that contain an optionally substituted cycloalkyl group having 3 or 4 ring carbon atoms.

Claims 30-31. (cancelled)

Claim 32. (previously presented) The photoresist of claim 29 wherein the polymer comprises alkyl ester groups.

Claim 33. (previously presented) The photoresist of claim 29 wherein the polymer comprises polymerized alkyl acrylate groups.

Claim 34. (currently amended) The photoresist of claim 33 wherein the alkyl acrylate groups comprise an optionally substituted cycloalkyl group having 3 or 4 ring carbon atoms.

Claim 35. (currently amended) The photoresist of claim 29 wherein the optionally substituted cycloalkyl group having 3 or 4 ring carbon atoms is a component of a polymerized acrylate.

Claim 36. (previously presented) The photoresist of claim 29 wherein the photoresist consists essentially of the photoacid generator compound and the polymer.

Claim 37. (previously presented) The photoresist of claim 29 wherein the photoresist consists essentially of the photoacid generator compound, the polymer and a base component.

Claim 38. (previously presented) An article of manufacture comprising a substrate having coated thereon a photoresist composition of claim 29.

Claim 39. (previously presented) The article of claim 38 wherein the substrate is a microelectronic wafer.